

MODULAR JACKS AND PLUGS: GDLPX Series

Vertical Low Profile Modular Jack

Product Features

Low Profile Design
Snap-In Board Retention Tabs
Fully Shielded for EMI/RFI Protection

Performance Specifications

Materials and Finish

Housing Material

PBT Thermoplastic, UL 94V-0 Rated,
Black Color

Shield Material

Copper Alloy, Nickel Plated

Contact Material

Phosphor Bronze, Gold Plating on Contact Area,
Tin Plated on Solder Area

Electrical Characteristics

Insulation Resistance

500 Megohms Min.

Dielectric Withstanding Voltage

1000V AC for 1 Minute

Contact Resistance

20 milliohms Max.

Current Rating

1.5A

Voltage Rating

125V DC

Mechanical Characteristics

Durability Rating

750 Mating Cycles Min.

Operating Temperature

0°C to 70°C

2D Drawing	IGES	STEP	3D PDF
Solder Profile	CofC RoHS Compliant	CofC REACH Compliant	UL Plastic File
Certificate of Origin	Check Stock	Request a Sample	Send Us An Email

Generated Part Number

Part Number Builder

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Series		Orientation	Shield Option	No. of Positions Contacts	Plating Option

Series

GDLPX - Low Profile Modular Jack

Orientation

P - Perpendicular

Shield Option

NS - Shielded

Number of Positions/Contacts

88 - 8 Positions / 8 Contacts

Plating Options

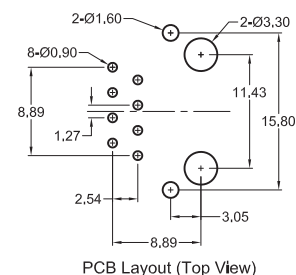
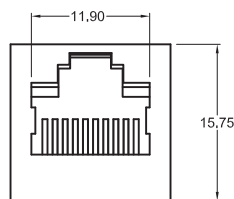
Blank - Gold Flash

50 - 50μ" Gold Plating

Contact Kycon for Other Options

GDLPX Series

Dimensions in mm



PCB Layout (Top View)

